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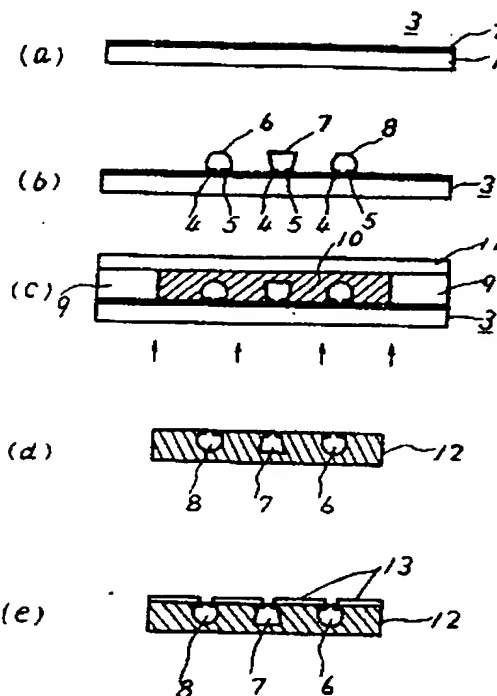
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TITLE : MANUFACTURE OF CIRCUIT MODULE



ABSTRACT : PURPOSE: To obtain a circuit module of the same extremely thin degree as the thickness of a chip type electronic parts by mounting in the shape that the parts are effectively buried in a substrate made of cured resin.

CONSTITUTION: A silicone resin film 2 is obtained on a glass plate 1, gelled to impart adhesive and mold releasing properties to the surface as a support 3. Electrodes 4, 5 sides are disposed at the prescribed positions on the support 3 of drawn trapezoidal or semicircular-sectional cylindrical chip type electronic parts 6-8. Spacers 9 made of Teflon are disposed, ultraviolet curable resin 10 is molded around the parts 6-8 on the support 3 in this state, a flat plate 11 made, for example, Teflon is coated thereon, and ultraviolet ray is emitted to cure the resin 10. Then, the support 3, the plate 11 and the spacers 9 are separated to obtain the parts 6-8 buried in a substrate 12. Then, silver paste is screen printed to form a desired conductor pattern 13.

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